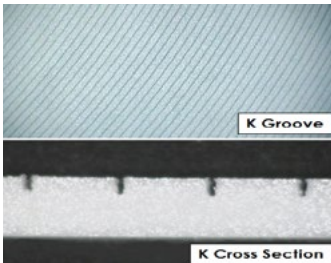


PUREON

Polishing pads

Advanced polyurethane with micropore structure

IC1000™



The IC1000 pad works effectively with slurries and conditioners to optimize CMP performance.



Pureon offers a variety of slurries in a wide range of viscosities and custom formulations to match IC1000 pads. We are happy to assist you in finding the best suitable products.

Advanced polyurethane pad with micropore structure for CMP

IC1000 pad is the industry-standard polishing pad for chemical mechanical planarization (CMP). The IC1000 pad is made of a rigid, micro-porous polyurethane material. These properties enable the IC1000 pad to deliver localized planarization, excellent removal rates, low global non-uniformity and low defectivity. The IC1000 pad works effectively with slurries and conditioners to optimize CMP performance in tungsten, copper, ILD, STI, and polysilicon processes.

Product specifications

Base material Urethane
 Shelf life 12 months
 Applications Beryllium, germanium, indium phosphide, nickel, polysilicon, sapphire, silicon carbide, tungsten, zinc selenide, copper, ILD, STI

Polishing pad	Base material	Compressibility %	Hardness	Hardness test	Thickness (mils)
IC1000	Urethane	2.25	57	Shore D	50
IC1010	Urethane	2.25	57	Shore D	80

Contact

sales@pureon.com

www.pureon.com/sales-contacts

Packing information

Pads are packaged face-to-face (polish side to polish side) and sealed inside a plastic bag to ensure cleanliness during transportation. The bags are taped to the side of the box to prevent the bag from slipping and damaging the pads. Pads should always remain flat. Bending pads during handling can cause wrinkles in the PSA and premature delamination of the release liner.

IC1000 highlights

- Industry standard for CMP.

Instructions

Handling

Apply only to a clean, dry surface at room temperature. If an appropriate solvent, such as isopropyl alcohol, is used to clean the platen after a pad removal, allow the platen to dry completely and return to room temperature before applying a new pad. Solvents remaining on the platen or an unusually cold platen will lower PSA adhesion.

When applying the pad to the platen, peel the release liner from one edge of the pad. Fold liner back approximately 2 inches. Align the pad with the edge of the platen and adhere. In one continuous movement, slowly peel the remaining release liner off the pad while pressing the pad down on the platen. The application should be smooth and uniform with even pressure from the pad mounting tool (such as a flat disk or hand roller).

Do not try to reposition pads with PSA adhesive.

Storage

Product should be stored and transported in the original packaging. The product should be stored in temperatures between 10 °C to 24 °C (50 °F to 75 °F) and <50 % humidity. Exposure for six (6) months or less to conditions between -17 °C to 48 °C (0 °F and 120 °F) and/or at relative humidity of up to 100 % will not impact the product performance as long as the release liner remains intact and attached to the PSA. If the product is exposed to temperatures and humidity outside the recommended conditions, it may still be acceptable for use. In all cases, the product should be allowed to return to normal room temperatures prior to use.

Disposal

Dispose of in accordance with all applicable local regulations.



Pureon offers a wide range of customized solutions. More information can be found on www.pureon.com/products/overview